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Global Integrated Circuits (IC) Packaging & Testing Market 2026 by Company, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Integrated Circuits (IC) Packaging & Testing market size was valued at US$ 100830 million in 2025 and is forecast to a readjusted size of US$ 140710 million by 2032 with a CAGR of 4.9% during review period.

A process wherein a semiconductor chip is packaged in a form suitable for the electronic device.

Semiconductor packaging is a process of protecting the chip from the external environment, and electrically packaging it to connect the terminals. The integrated circuit (IC) is a component of circuit boards and electronic devices. ICs need to be electrically packaged in a form fitting to where they’re installed. They are responsible for interconnects, supplying electrical power, and heat dissipation. Packaging also protects the semiconductor chips, shielding the integrated circuits from external factors such as high temperatures, impurities, and physical impact. Each chip is tested to verify normal operation after the packaging process has been completed. This testing is called the package test. The package test is conducted on finished chip products. Chips are placed in a testing apparatus and tested under various conditions to sort out defective products.

The semiconductor industry chain mainly includes three major processes: chip design, chip manufacturing, and packaging and testing. According to the different business models of packaging and testing companies, the business model is divided into two types: IDM and OSAT.

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This report studies the Integrated Circuits (IC) Packaging and Testing Service.

The key IDMs include Samsung-Memory, Intel, SK Hynix, Micron Technology, Texas Instruments (TI), STMicroelectronics, Kioxia, Sony Semiconductor Solutions Corporation (SSS), Infineon, NXP, Analog Devices, Inc. (ADI), Renesas Electronics, Microchip Technology and Onsemi; and the key OSATs include ASE (SPIL), Amkor, JCET (STATS ChipPAC), Tongfu Microelectronics (TFME), Powertech Technology Inc. (PTI), Carsem, King Yuan Electronics Corp. (KYEC), SFA Semicon, Unisem Group, Chipbond Technology Corporation and ChipMOS TECHNOLOGIES, etc.

Following a strong growth of 26.2 percent in the year 2021, WSTS revised it down to a single digit growth for the worldwide semiconductor market in 2022 with a total size of US$580 billion, up 4.4 percent. WSTS lowered growth estimation as inflation rises and end markets seeing weaker demand, especially those exposed to consumer spending. While some major categories are still double-digit year-over-year growth in 2022, led by Analog with 20.8 percent, Sensors with 16.3 percent, and Logic with 14.5 percent growth. Memory declined with 12.6 percent year over year. In 2022, all geographical regions showed double-digit growth except Asia Pacific. The largest region, Asia Pacific, declined 2.0 percent. Sales in the Americas were US$142.1 billion, up 17.0% year-on-year, sales in Europe were US$53.8 billion, up 12.6% year-on-year, and sales in Japan were US$48.1 billion, up 10.0% year-on-year. However, sales in the largest Asia-Pacific region were US$336.2 billion, down 2.27% year-on-year.

This report is a detailed and comprehensive analysis for global Integrated Circuits (IC) Packaging & Testing market. Both quantitative and qualitative analyses are presented by company, by region & country, by Business Model and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Integrated Circuits (IC) Packaging & Testing market size and forecasts, in consumption value ($ Million), 2021-2032

Global Integrated Circuits (IC) Packaging & Testing market size and forecasts by region and country, in consumption value ($ Million), 2021-2032

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Global Integrated Circuits (IC) Packaging & Testing market size and forecasts, by Business Model and by Application, in consumption value ($ Million), 2021-2032

Global Integrated Circuits (IC) Packaging & Testing market shares of main players, in revenue ($ Million), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Integrated Circuits (IC) Packaging & Testing

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Integrated Circuits (IC) Packaging & Testing market based on the following parameters - company overview, revenue, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Samsung, Intel, SK Hynix, Micron Technology, Texas Instruments (TI), STMicroelectronics, Kioxia, Western Digital, Infineon, NXP, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market segmentation

Integrated Circuits (IC) Packaging & Testing market is split by Business Model and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for Consumption Value by Business Model and by Application. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Business Model

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IDM

OSAT

Market segment by Application

Analog IC Packaging & Testing

MPU & MCUs IC Packaging & Testing

Logic IC Packaging & Testing

Memory IC Packaging & Testing

Market segment by players, this report covers

Samsung

Intel

SK Hynix

Micron Technology

Texas Instruments (TI)

STMicroelectronics

Kioxia

Western Digital

Infineon

NXP

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Analog Devices, Inc. (ADI)

Renesas

Microchip Technology

Onsemi

Sony Semiconductor Solutions Corporation

Panasonic

Winbond

Nanya Technology

ISSI (Integrated Silicon Solution Inc.)

Macronix

Giantec Semiconductor

Sharp

Magnachip

Toshiba

JS Foundry KK.

Hitachi

Murata

Skyworks Solutions Inc

Wolfspeed

Littelfuse

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Diodes Incorporated

Rohm

Fuji Electric

Vishay Intertechnology

Mitsubishi Electric

Nexperia

Ampleon

CR Micro

Hangzhou Silan Integrated Circuit

ASE (SPIL)

Amkor

JCET (STATS ChipPAC)

Tongfu Microelectronics (TFME)

Powertech Technology Inc. (PTI)

Carsem

King Yuan Electronics Corp. (KYEC)

SFA Semicon

Unisem Group

Chipbond Technology Corporation

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ChipMOS TECHNOLOGIES

OSE CORP.

Sigurd Microelectronics

Natronix Semiconductor Technology

Nepes

Forehope Electronic (Ningbo) Co.,Ltd.

Union Semiconductor(Hefei)Co., Ltd.

Hefei Chipmore Technology Co.,Ltd.

HT-tech

Chippacking

Market segment by regions, regional analysis covers

North America (United States, Canada and Mexico)

Europe (Germany, France, UK, Russia, Italy and Rest of Europe)

Asia-Pacific (China, Japan, South Korea, India, Southeast Asia and Rest of Asia-Pacific)

South America (Brazil, Rest of South America)

Middle East & Africa (Turkey, Saudi Arabia, UAE, Rest of Middle East & Africa)

The content of the study subjects, includes a total of 13 chapters:

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Chapter 1, to describe Integrated Circuits (IC) Packaging & Testing product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top players of Integrated Circuits (IC) Packaging & Testing, with revenue, gross margin, and global market share of Integrated Circuits (IC) Packaging & Testing from 2021 to 2026.

Chapter 3, the Integrated Circuits (IC) Packaging & Testing competitive situation, revenue, and global market share of top players are analyzed emphatically by landscape contrast.

Chapter 4 and 5, to segment the market size by Business Model and by Application, with consumption value and growth rate by Business Model, by Application, from 2021 to 2032.

Chapter 6, 7, 8, 9, and 10, to break the market size data at the country level, with revenue and market share for key countries in the world, from 2021 to 2026.and Integrated Circuits (IC) Packaging & Testing market forecast, by regions, by Business Model and by Application, with consumption value, from 2027 to 2032.

Chapter 11, market dynamics, drivers, restraints, trends, Porters Five Forces analysis.

Chapter 12, the key raw materials and key suppliers, and industry chain of Integrated Circuits (IC) Packaging & Testing.

Chapter 13, to describe Integrated Circuits (IC) Packaging & Testing research findings and conclusion.

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